

0.4	17.8	16.9	15.2	53309-4029	40	
0.8	17.0	16.1	14.4	-3829	38	
0.4	16.2	15.3	13.6	-3629	36	
0.8	15.4	14.5	12.8	-3429	34	
0.4	14.6	13.7	12.0	-3229	32	
0.8	13.8	12.9	11.2	-3029	30	
0.4	13.0	12.1	10.4	-2829	28	
0.8	12.2	11.3	9.6	-2629	26	
0.4	11.4	10.5	8.8	-2429	24	
0.8	10.6	9.7	8.0	-2229	22	
0.4	9.8	8.9	7.2	-2029	20	
0.8	9.0	8.1	6.4	-1829	18	
0.4	8.2	7.3	5.6	-1629	16	
0.8	7.4	6.5	4.8	-1429	14	
0.4	6.6	5.7	4.0	-1229	12	
0.8	5.8	4.9	3.2	53309-1029	10	
MODEL NO.	D	C	B	A	MATERIAL NO.	極数 CKT.

注記 NOTES

1. 嵌合相手 : 52465,52588 シリーズ
MATE WITH : 52465,52588 SERIES
2. ウエハーの C から隣接するピンの C 迄の位置を示す。
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.
3. 本製品は 53309-***27 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-***27

REVISED EC NO: J2007-3336 DRWN: YAMADA01 CHKD: KYOUDA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN.WAFER ASS'Y R/A SMT(WITHOUT BOSS) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/10	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/10	DOCUMENT NO. SD-53309-011	SHEET NO. 1 OF 2	
ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE			
A	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F

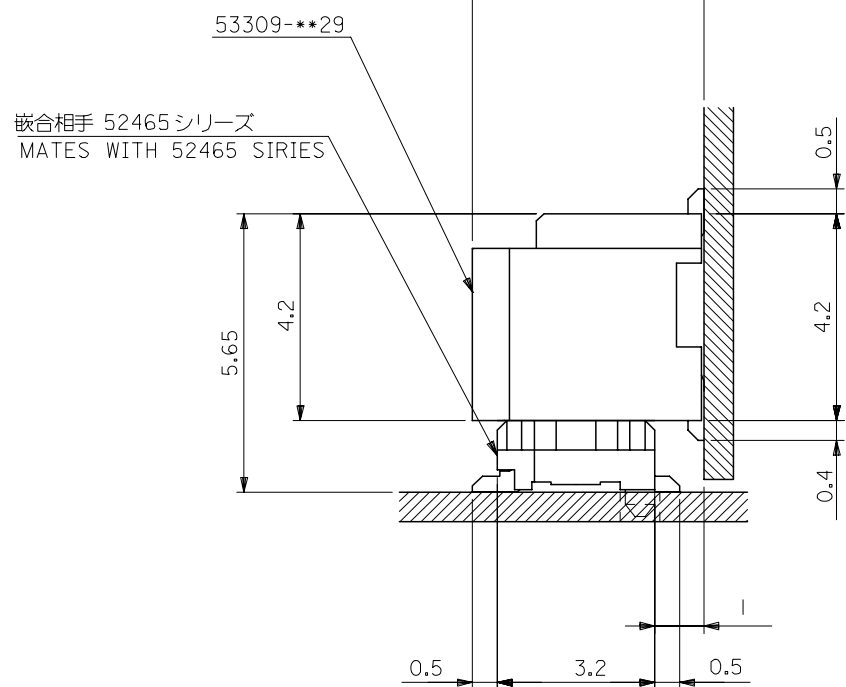
E

D

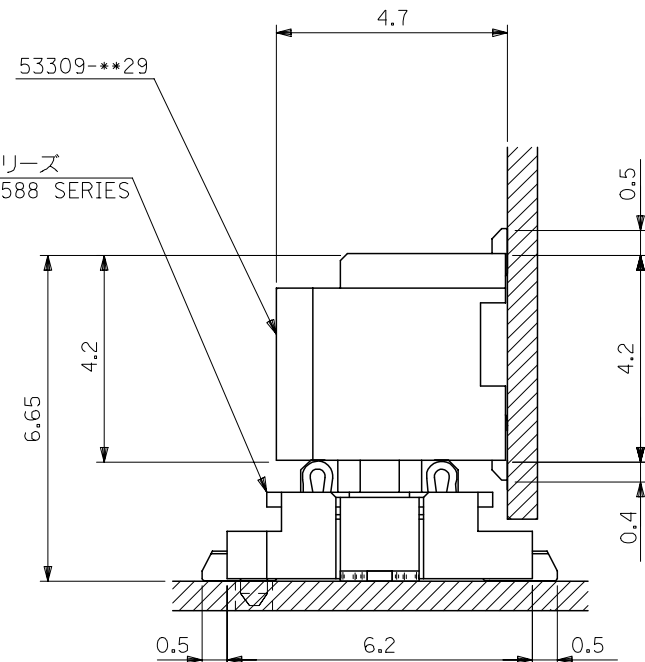
C

B

A

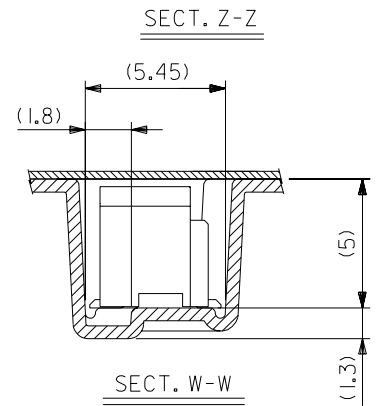
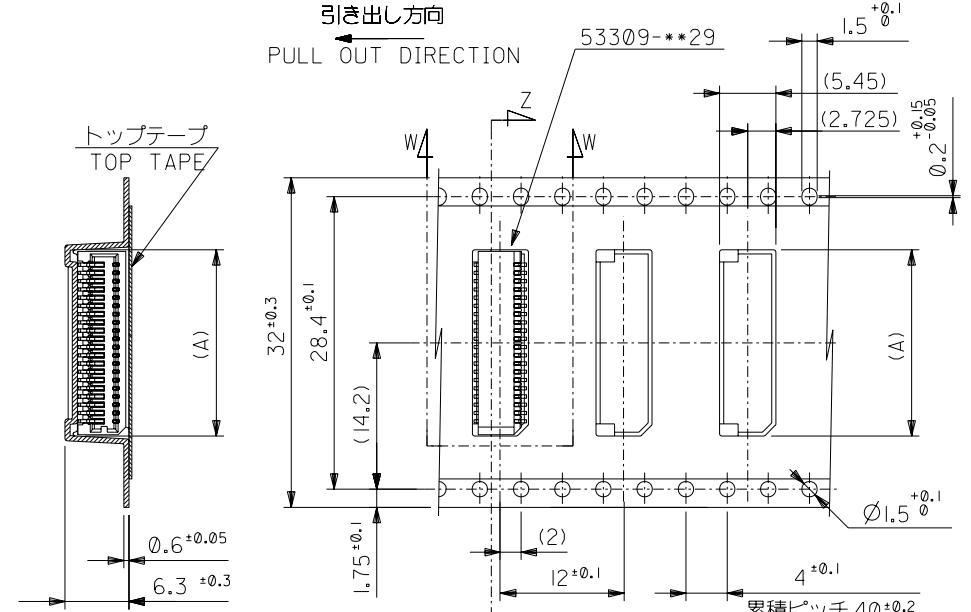
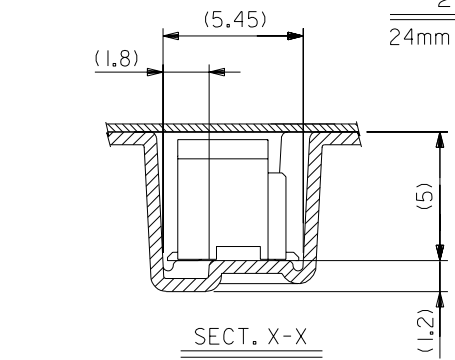
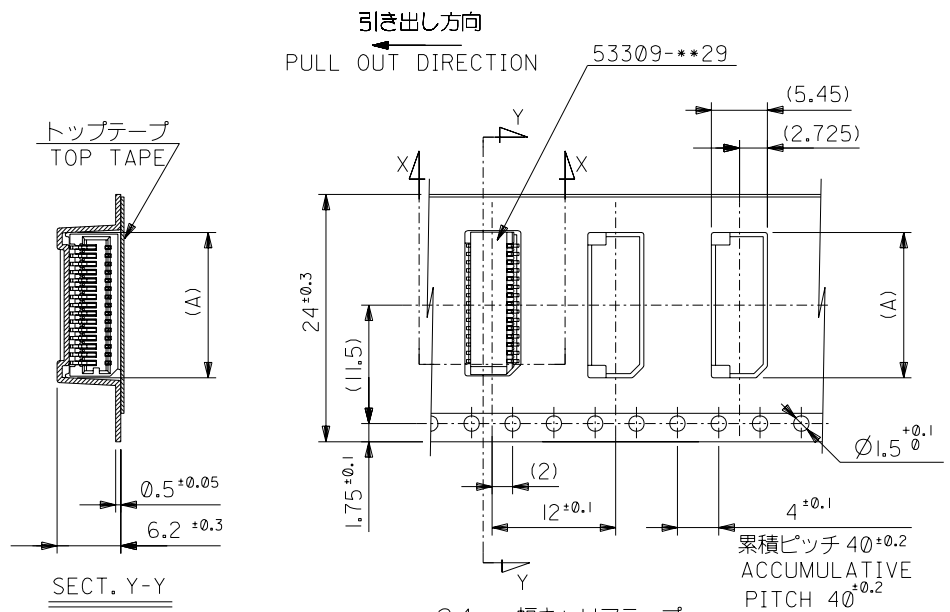


嵌合状態図 (参考)
MATED DRAWING(REF.)



嵌合状態図 (参考)
MATED DRAWING(REF.)

REVISED EC NO: J2007-3336 DRWN: YAMADA01 2007/06/06 CHKDK: TOYODA 2007/06/08 APPR: NUKITA 2007/06/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. NINOMIYA		DATE 2004/03/10	TITLE 0.8 B/B CONN. WAFER ASS'Y R/A SMT(WITHOUT BOSS) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO		DATE 2004/03/10	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO		DATE 2004/03/10	DOCUMENT NO. SD-53309-011		
	ANGULAR	±3 °	MATERIAL NO.		SEE SHEET 1		SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



24	29.4	25.4	16.5	53309-3670	36
			15.7	53309-3470	34
			14.9	53309-3270	32
			14.1	53309-3070	30
			13.3	53309-2870	28
			12.5	53309-2670	26
			11.7	53309-2470	24
			10.9	53309-2270	22
			10.1	53309-2070	20
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

53309-***70					
MODEL NO.					
角度 ANGLE	±3°				
30以上 OVER	+0.3				
10以上 OVER	+0.25				
30未満 UNDER					
10未満 UNDER	+0.2				
一般公差 GENERAL TOLERANCES		記号 LTR	新規作成 RELEASED (J2004-2995)	M.N. K.T.	04/03/10
			変更内容 REVISION RECORD	日付 DATE	

32	37.4	33.4	18.1	53309-4070	40
			17.3	53309-3870	38
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

材料 MATERIAL
SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2

仕上げ FINISH —

適用電線範囲 WIRE RANGE —

被覆外径 INS. RANGE —

DRAWN BY 04/03/10 M.NINOMIYA
CHK'D BY 04/03/10 K.TOJO

APP'D BY 04/03/10 M.SASAO

材料 M.OLEX

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BtB Wafer Assy
RA SMT Without Boss
Embstp Pkg
-LEAD FREE-

DWG. NO. (SHEET 2 OF 2) REV
SD-53309-012 0